

## CLAIMS

1. (Currently Amended) An ~~A multilevel mold for~~ imprint lithography mold comprising a multilevel mold containing a negative ~~that contains~~ a relief image of a dual damascene structure having:

a substrate coated with a trilayer hardmask stack;

said trilayer hardmask stack having a plurality of layers including:

a bottom hardmask layer, having a composition suitable to be an etchstop layer,

said bottom layer being in contact with said substrate;

a middle hardmask layer having a composition suitable to print a negative line-level pattern, said line level pattern forming the basis for the horizontal line levels existing within said mold, said middle layer being in contact with an exposed surface of said bottom etchstop layer;

a top layer having a composition suitable to print a negative via level pattern and having an upper and a lower surface, said lower surface of said top layer being in contact with an exposed surface of said middle layer;

said upper surface of said top layer of said trilayer hardmask stack having a removable negative via level pattern which forms a topographical pattern, said pattern forming the basis for the multilevel vertical depth trenches existing within said mold;

a resist coating on said upper surface of said top layer of said hardmask stack, said resist coating being patterned with a negative line level pattern;

said mold containing multilevel mold elements through said trilayer hardmask stack and said substrate aligned with and corresponding to said negative line level pattern and with and to said negative via level pattern resulting in a negative of a dual damascene-like structure.

2. (Withdrawn) A method for producing a multilevel mold that contains the relief image of a dual-damascene structure or the negative relief image of a dual-damascene structure.